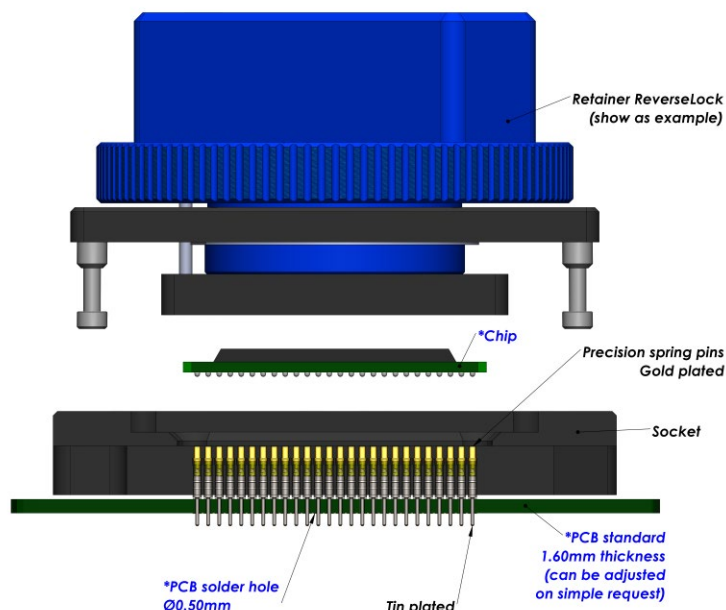
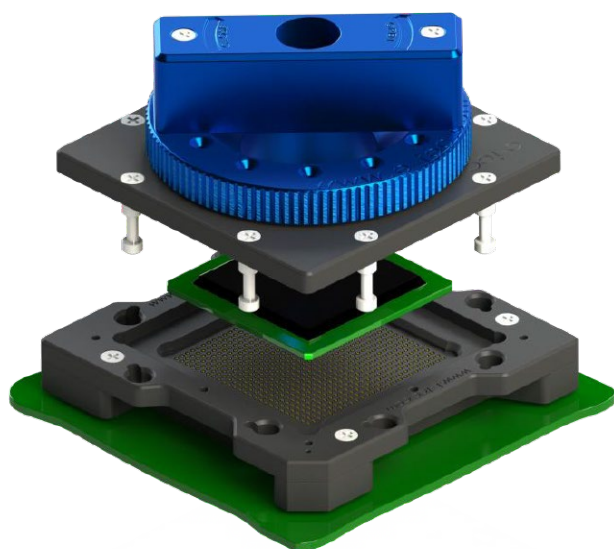


# Through-hole (THT) soldering Test Socket

For BGA / Bumped chip / WLCSP / eMMC Package

1.00 mm pitch (from 1.00 mm up to 1.26 mm)



**E-tec Interconnect AG is the world leading Test socket manufacturer**

The Through-hole socket uses the same footprint as your chip. Socket is simply placed and wave soldered onto the PCB in the same way as the chip and it only requires a small amount of additional board space. Through-hole sockets are available with all retention systems. Please note, we will always request the chip data to ensure we offer a compatible socket.

Specifications contact type code 1070			
Application	Through-hole technology	Force	25 gr
Mounting	THT	Current rating	1.8 A
Bandwidth (GHz@-1dB)	3.4 GHz	Capacitance pF	1.03 pF
Contact resistance	<100mOhm	Inductance nH	1.80 nH
Chip contact tip shape	Single Point tip or Concave tip	Temperature range	-55°C to +150°C
PCB tip shape	Through-hole	Mating cycles	100 K

## How to order

**BU # #### -107# - ##### #5 #**

### Shape of tip

U : Concave

#### Options:

P : Pointed

S : Spring

C : Crown

### Nbr of contacts

Depends on ballcount of chip

### Contact type

70 : Standard THT

72 : Special THT to plug into MGS adapters

### Plating

95: Tin / Gold

55: Gold / Gold

Other on request

### Option code (see page 16-19)

D : Dead bug

M : Multi frames

U : Multi packages

S : Custom opening slot

L : Locating pegs

A : Alignment plate

H : Heatsink

F : Fan + Heatsink

P : Thermal drain pad

W : Transparent lid

I : Steel retention lid

B : Aluminium retention lid

T : Torque tool fixture

G : Handling button

### Retention frame type (Lid) (see page 12-15)

W: TwistLock

F : FastLock

B : SpringLock

H : Open Clamshell Alu (<200 contacts)

J : Clamshell Alu (>200 contacts)

L : Open Lever Clamshell Alu (>200 contacts)

S : ScrewLock

Q : Open QuickLock (<200 contacts)

D : QuickLock (>200 contacts)

M : Injection Molded ClamShell

R : ReverseLock

T : SlimLock

### Grid code / Config. code

Will be given by the factory after receipt of the chip datasheet